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<b>TITLE:</b> 128LD TQFP, 14 X 14 X 1.0 PKG, 0.4 PITCH, 8.3 X 8.3 EXPOSED PAD		DOCUMENT NO: 98ASA10784D      REV: D STANDARD: NON-JEDEC SOT1522-1      15 JAN 2016






NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

4.  DIMENSION TO BE DETERMINED AT SEATING PLANE C.

5.  THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 MM.

6.  THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.

7.  EXACT SHAPE OF EACH CORNER IS OPTIONAL.

8.  THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 MM AND 0.25 MM FROM THE LEAD TIP.

9.  SOLDERABLE AREA WITHIN THE INNER GROOVE OF THE PACKAGE IS GUARANTEED TO BE 7.4X7.4MM.SQ. THE PACKAGE MAXIMUM EXPOSED PAD AREA IS 9.0X9.0MM.SQ WHICH INCLUDES THE DOUBLE GROOVES.

10. LEADFRAME PART NUMBER APPLIED IS 17ASA10156D700/17ASA10156D702.

11.  DISTANCE BETWEEN PACKAGE BODY AND EVERY LEAD TIP SHALL BE MAINTAINED AT MINIMUM 0.03MM.

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